

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7037757

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHUNSUKE KONDO	06/14/2021
YUYA OTSUKA	11/16/2021
MAYUMI KOMINE	10/11/2021
KEISUKE INOUE	09/23/2021
RECEIVING PARTY DATA	
Name:	SHOWA DENKO MATERIALS CO., LTD.
Street Address:	9-2, MARUNOUCHI 1-CHOME, CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	100-6606
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17251531
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3125777000
Email:	rcaron@fitcheven.com
Correspondent Name:	ROBERT CARON
Address Line 1:	120 SOUTH LASALLE STREET
Address Line 4:	CHICAGO, ILLINOIS 60603
ATTORNEY DOCKET NUMBER:	20374-150619-US
NAME OF SUBMITTER:	GILES N. TURNER
SIGNATURE:	/Giles N. Turner/
DATE SIGNED:	11/22/2021
Total Attachments: 8	
source=150619_Asnmts#page1.tif	
source=150619_Asnmts#page2.tif	
source=150619_Asnmts#page3.tif	

source=150619_Asnmts#page4.tif

source=150619_Asnmts#page5.tif

source=150619_Asnmts#page6.tif

source=150619_Asnmts#page7.tif

source=150619_Asnmts#page8.tif

ASSIGNMENT

Whereas, I/we,
Name

Address

1) Shunsuke KONDO	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
2) Yuya OTSUKA	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
3) Mayumi KOMINE	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
4) Keisuke INOUE	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan

hereinafter called assignor(s), have invented certain improvements in
POLISHING LIQUID AND POLISHING METHOD

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on December 11, 2020, Serial No. 17/251531; and

Whereas

Showa Denko Materials Co., Ltd.
9-2, Marunouchi 1-chome,
Chiyoda-ku, Tokyo 100-6606 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

In the event that the patent application filing date or serial number is not known at the time this Assignment is executed, I/WE hereby grant permission to the attorneys of record in the patent application to fill in the filing date and/or serial number above, and to record this Assignment after such information is added.

INVENTORS

DATE SIGNED

1) :	<u>Shunsuke Kondo</u>	<u>June 14, 2021</u>
Name :	Shunsuke KONDO	
2) :	_____	_____
Name :	Yuya OTSUKA	

3) : _____
Name : Mayumi KOMINE

4) : _____
Name : Keisuke INOUE

ASSIGNMENTWhereas, I/we,
NameAddress

1) Shunsuke KONDO	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
2) Yuya OTSUKA	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
3) Mayumi KOMINE	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
4) Keisuke INOUE	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan

hereinafter called assignor(s), have invented certain improvements in
POLISHING LIQUID AND POLISHING METHOD

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on December 11, 2020, Serial No. 17/251531; and

Whereas

Showa Denko Materials Co., Ltd.
9-2, Marunouchi 1-chome,
Chiyoda-ku, Tokyo 100-6606 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

In the event that the patent application filing date or serial number is not known at the time this Assignment is executed, I/WE hereby grant permission to the attorneys of record in the patent application to fill in the filing date and/or serial number above, and to record this Assignment after such information is added.

INVENTORSDATE SIGNED

1) :	_____	_____
Name :	Shunsuke KONDO	
2) :	<u>Yuya Otsuka</u>	<u>2021. 11. 16</u>
Name :	Yuya OTSUKA	

3) : _____
Name : Mayumi KOMINE

4) : _____
Name : Keisuke INOUE

ASSIGNMENT

Whereas, I/we,

<u>Name</u>	<u>Address</u>
1) Shunsuke KONDO	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
2) Yuya OTSUKA	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
3) Mayumi KOMINE	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
4) Keisuke INOUE	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan

hereinafter called assignor(s), have invented certain improvements in
POLISHING LIQUID AND POLISHING METHOD

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on December 11, 2020, Serial No. 17/251531; and

Whereas

Showa Denko Materials Co., Ltd.
9-2, Marunouchi 1-chome,
Chiyoda-ku, Tokyo 100-6606 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

In the event that the patent application filing date or serial number is not known at the time this Assignment is executed, I/WE hereby grant permission to the attorneys of record in the patent application to fill in the filing date and/or serial number above, and to record this Assignment after such information is added.

INVENTORS

DATE SIGNED

1) : _____
Name : Shunsuke KONDO

2) : _____
Name : Yuya OTSUKA

3) : Mayumi Komine Oct. 11, 2021
Name : Mayumi KOMINE

4) : _____
Name : Keisuke INOUE

ASSIGNMENT

Whereas, I/we,
Name

Address

1) **Shunsuke KONDO**

c/o Showa Denko Materials Co., Ltd.,
9-2, Marunouchi 1-chome,
Chiyoda-ku, Tokyo 100-6606 Japan

2) **Yuya OTSUKA**

c/o Showa Denko Materials Co., Ltd.,
9-2, Marunouchi 1-chome,
Chiyoda-ku, Tokyo 100-6606 Japan

3) **Mayumi KOMINE**

c/o Showa Denko Materials Co., Ltd.,
9-2, Marunouchi 1-chome,
Chiyoda-ku, Tokyo 100-6606 Japan

4) **Keisuke INOUE**

c/o Showa Denko Materials Co., Ltd.,
9-2, Marunouchi 1-chome,
Chiyoda-ku, Tokyo 100-6606 Japan

hereinafter called assignor(s), have invented certain improvements in
POLISHING LIQUID AND POLISHING METHOD

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on December 11, 2020, Serial No. 17/251531; and

Whereas

Showa Denko Materials Co., Ltd.
9-2, Marunouchi 1-chome,
Chiyoda-ku, Tokyo 100-6606 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

In the event that the patent application filing date or serial number is not known at the time this Assignment is executed, I/WE hereby grant permission to the attorneys of record in the patent application to fill in the filing date and/or serial number above, and to record this Assignment after such information is added.

INVENTORS

DATE SIGNED

1) : _____
Name : Shunsuke KONDO

2) : _____
Name : Yuya OTSUKA

3) :

Name :

Mayumi KOMINE

4) :

Name :

Keisuke Inoue

Keisuke INOUE

September 23, 2021